



Technical Data Sheet

1206 Package Chip LEDs with Inner Lens

11-21SYGC/S530-XX/TR8

Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.

Descriptions

- The 11-21 SMD Taping is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

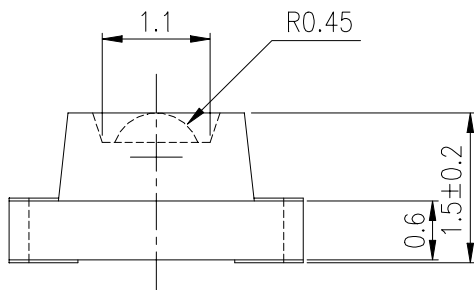
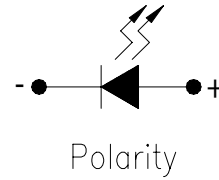
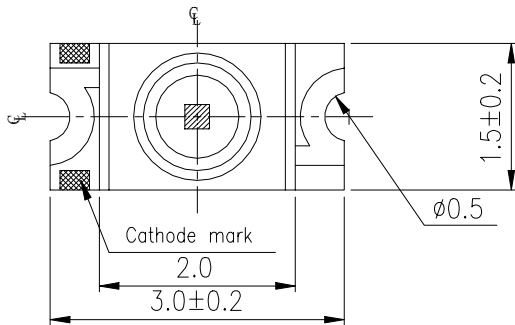
- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.



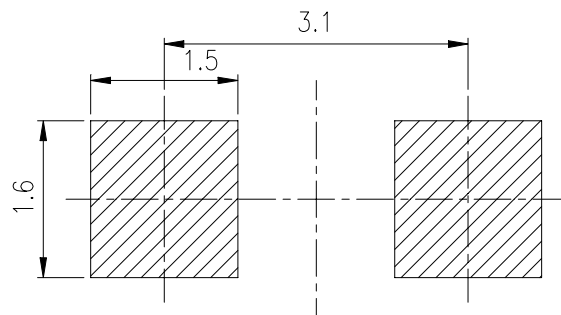
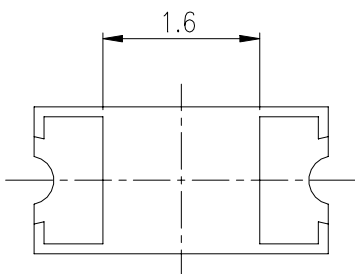
Device Selection Guide

Chip		Lens Color
Material	Emitted Color	
AlGaInP	Super Yellow Green	Water Clear

Package Outline Dimensions



For reflow soldering (propose)



Note: Tolerances Unless Dimension $\pm 0.1\text{mm}$, Angle $\pm 0.5^\circ$,Unit = mm

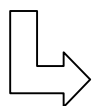
Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40~ +90	°C
Soldering Temperature	T _{sol}	260 (for 5 second)	°C
Electrostatic Discharge	ESD	2000	V
Power Dissipation	P _d	60	mW
Peak Forward Current (Duty 1/10 @1KHz)	I _F	60	mA

Electro-Optical Characteristics (Ta=25°C)

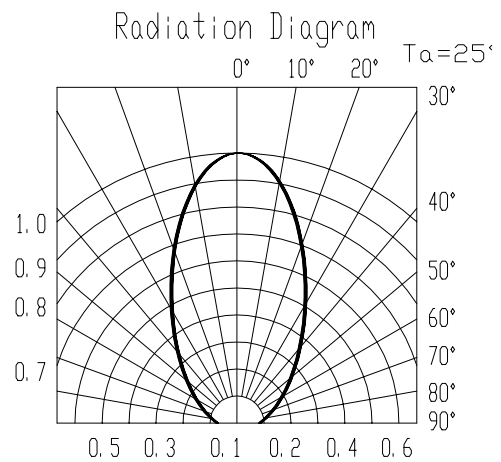
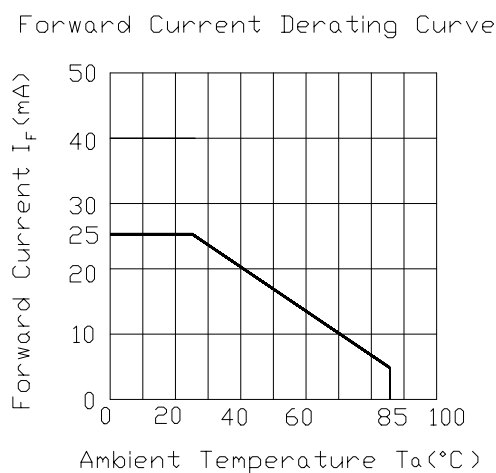
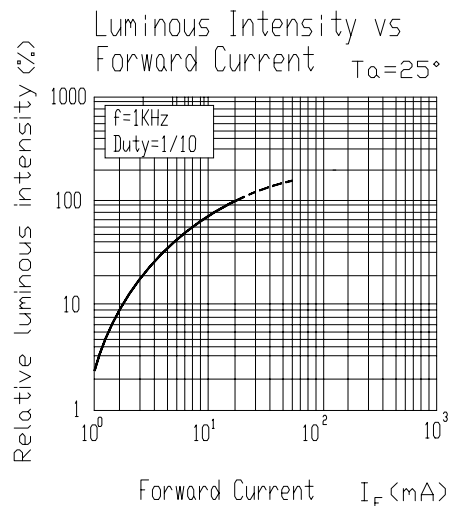
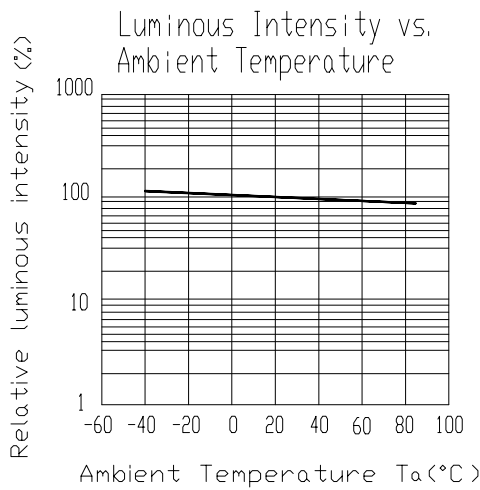
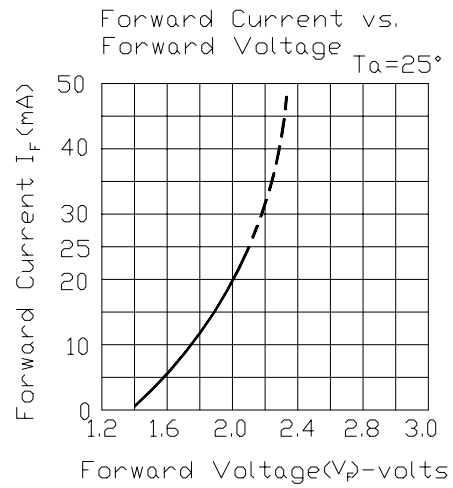
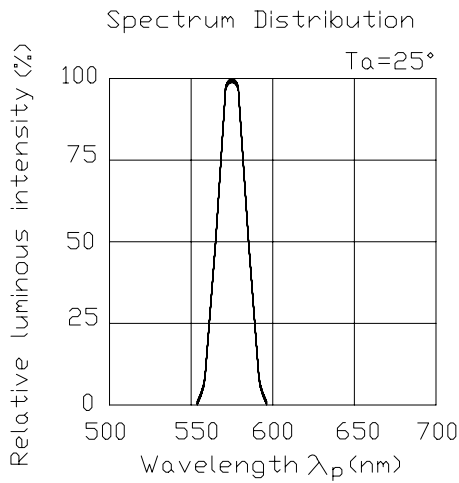
Parameter	Symbol	*Chip Rank	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	E1	19	29	-----	mcd	I _F =20 mA
		E2	29	39	-----		
		E3	39	52	-----		
		E4	52	62	-----		
Viewing Angle	2θ 1/2	-----	-----	60	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	-----	575	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	-----	-----	573	-----	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	-----	20	-----	nm	I _F =20mA
Forward Voltage	V _F	-----	-----	2.0	2.4	V	I _F =20mA
Reverse Current	I _R	-----	-----	-----	10	μA	V _R =5V

***11-21SYGC/S530-XX/TR8**



Chip Rank

Typical Electro-Optical Characteristics Curves

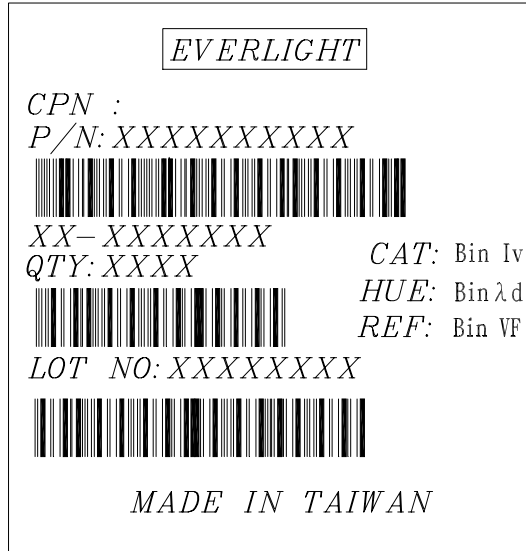


■ **Label explanation**

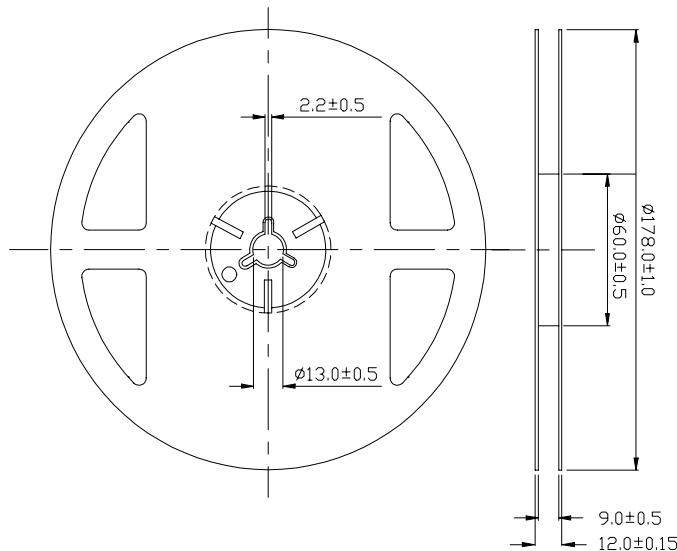
CAT: Luminous Intensity (mcd)

HUE: Dom. Wavelength (nm)

REF: Forward Voltage (V)

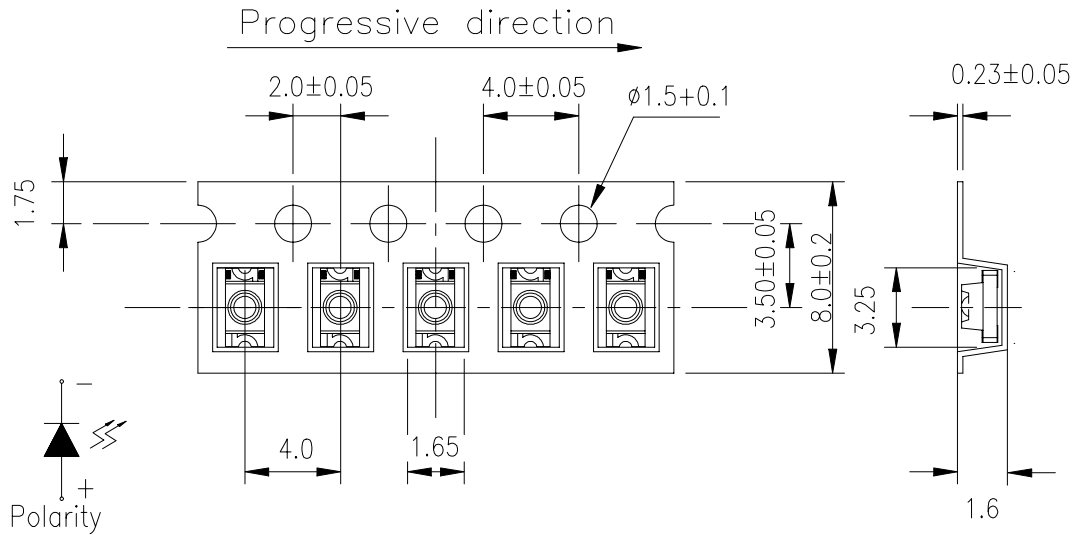


■ **Reel Dimensions**



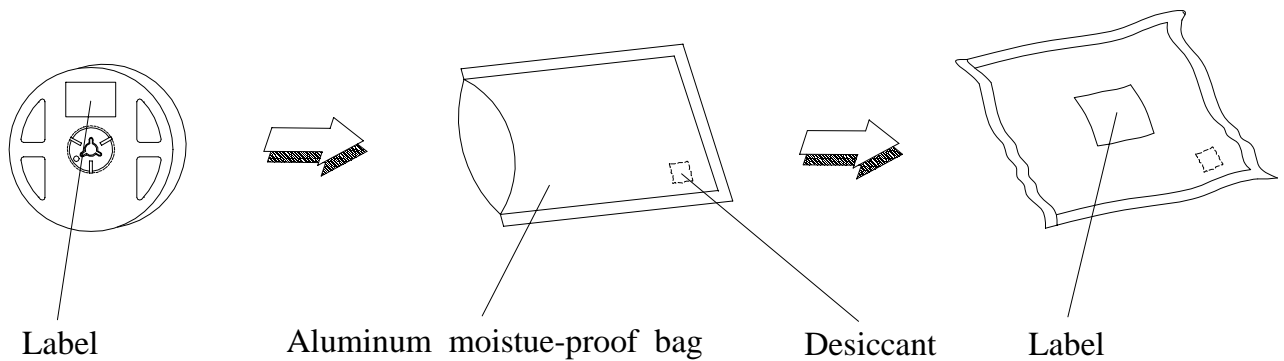
Note: Tolerances Unless Dimension $\pm 0.1\text{mm}$, Angle $\pm 0.5^\circ$,Unit = mm

■ **Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel**



Note: Tolerances

■ **Moisture Resistant Packaging**



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90 %

LTPD : 10 %

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow	Temp. : 240°C ± 5°C Min. 5 sec.	6 min.	22 Pcs.	0/1
2	Temperature Cycle	H : +100°C 15min. ∫ 5 min. L : -40°C 15min.	300 Cycles	22 Pcs.	0/1
3	Thermal Shock	H : +100°C 5min. ∫ 10 sec. L : -10°C 5min.	300 Cycles	22 Pcs.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 Pcs.	0/1
5	Low Temperature Storage	Temp. : -55°C	1000 Hrs.	22 Pcs.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 Pcs.	0/1
7	High Temperature / High Humidity	85°C/R.H85%	1000 Hrs.	22 Pcs.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage time

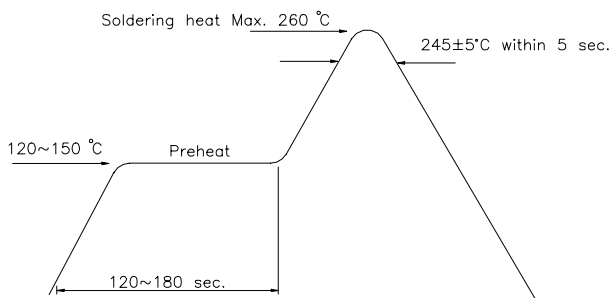
2.1 The operation of Temperature and RH are : 5°C~35°C, RH60%.

2.2 Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccating agent. Considering the tape life , we suggest our customers to use our products within a year(from production date).

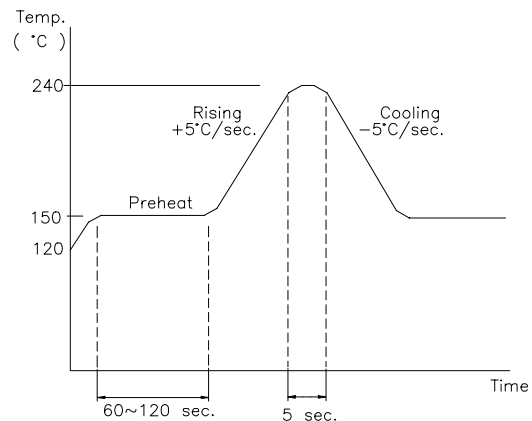
2.3 If opened more than one week in an atmosphere 5°C~35°C, RH 60%, they should be treated at 60°C± 5°C for 15hrs.

2.4 When you discover that the desiccant in the package has a pink color (Normal = blue) , you should treat them in the same conditions as 2.3.

Soldering heat



Reflow Temp / Time

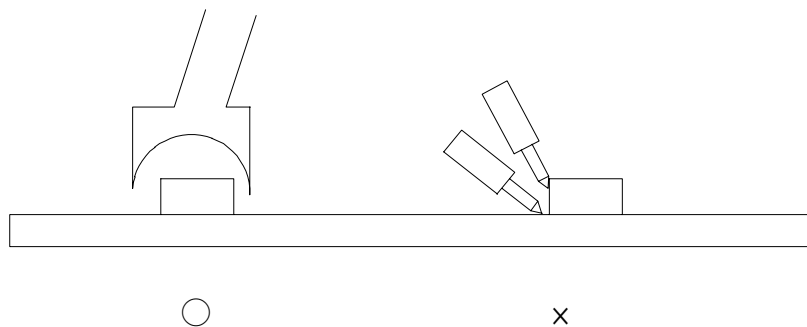


Soldering Iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter (+10°C → -1sec). Power dissipation of Iron should be smaller than 15 W , and temperature should be controllable. Surface temperature of the device should be under 230 °C .

Rework

1. Customer must finish rework within 5 sec under 245°C.
2. The head of iron can not touch copper foil.
3. Twin-head type is preferred.



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